



Material Composition Declaration

EPC2032

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	18.6 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	13.9274	74.88	77.69	748850
	Silicon oxide	7631-86-9	0.0743	0.40		3993
	Silicon nitride	12033-89-5	0.0269	0.14		1447
	Gallium nitride	25617-97-4	0.0885	0.48		4757
	Aluminum	7429-90-5	0.1437	0.77		7725
	Aluminum nitride	24304-00-5	0.0213	0.11		1148
	Titanium	7440-32-6	0.0035	0.02		186
	Titanium nitride	25583-20-4	0.0130	0.07		699
	Copper	7440-50-8	0.0048	0.03		257
	Tungsten	7440-33-7	0.0049	0.03		263
	Polyimide		0.1403	0.75		7546
Under Bump Metal	Titanium	7440-32-6	0.0017	0.01	0.77	91
	Nickel	7440-02-0	0.0000	0.00		0
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.1417	0.76		7617
Solder Bump	Tin	7440-31-5	3.8262	20.57	21.54	205728
	Silver	7440-22-4	0.1603	0.86		8617
	Copper	7440-50-8	0.0200	0.11		1077
Sum in total:			18.6	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.